

**IIS-064**

**Application of Nanotechnology to Develop Conducting/Strong Bonding Adhesives  
for Use in MEMS Devices**

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**Industry Participants**

ATOFINA, Polysciences

**Abstract**

This project will provide a greater understanding of the use of nanotechnology to develop better adhesives with critical attributes for MEMS applications. The project will deliver several custom formulated conductive adhesives to be evaluated by Bridge Semiconductor as well as a final formulation that may be commercially supplied by Polysciences using additives supplied by ATOFINA. All three companies are based in Pennsylvania. Milestones include evaluating the properties of the adhesive currently used by Bridge Semiconductor as well determining the properties needed for a reliable infrared focal plane array.